

## DESCRIPTION

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

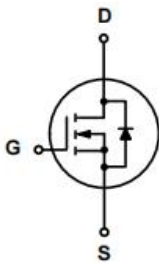
## GENERAL FEATURES

- $V_{DS}=30V, I_D=80A$   
 $R_{DS(ON)}(Typ.)=3.7m\Omega @ V_{GS}=10V$   
 $R_{DS(ON)}(Typ.)=6m\Omega @ V_{GS}=4.5V$
- Improved dv/dt capability
- 100% EAS Guaranteed
- Fast switching

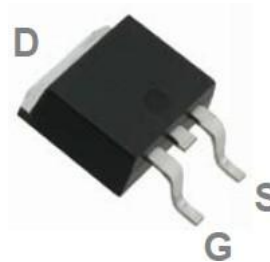
## APPLICATION

- NB / VGA /  $V_{CORE}$
- POL Applications
- SMPS 2<sup>nd</sup> SR

## PINOUT



Schematic diagram



TO-252 Top View

## ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXD3080K	-55°C to 150°C	TO-252	-

## ABSOLUTE MAXIMUM RATINGS ( $T_C=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_C=25^\circ C$ )	$I_D$	80	A
Continuous Drain Current ( $T_C=100^\circ C$ )	$I_D$	51	A
Pulsed Drain Current <sup>(Note1)</sup>	$I_{DM}$	320	A
Single Pulsed Avalanche Energy <sup>(Note2)</sup>	$E_{AS}$	88	mJ
Single Pulsed Avalanche Current <sup>(Note2)</sup>	$I_{AS}$	42	A
Power Dissipation ( $T_C=25^\circ C$ )	$P_D$	54	W
Power Dissipation (Derate above 25°C)	$P_D$	0.43	W/°C
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 175	°C
Thermal Resistance, Junction-to-Case <sup>(Note1)</sup>	$R_{\theta JC}$	2.3	°C/W
Thermal Resistance, Junction-to-Ambient <sup>(Note1)</sup>	$R_{\theta JA}$	62	°C/W

Note 1. Repetitive Rating : Pulsed width limited by maximum junction temperature.

Note 2.  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=42A, R_G=25\Omega, \text{Starting } T_J=25^\circ C$ .



**ELECTRICAL CHARACTERISTICS**( $T_J=25^{\circ}\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V$	-	-	1	$\mu A$
		$V_{DS}=24V, V_{GS}=0V, T_J=125^{\circ}\text{C}$	-	-	10	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.6	2.5	V
Drain-Source On-State Resistance <sup>(Note1)</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=30A$	-	3.7	5	m $\Omega$
		$V_{GS}=4.5V, I_D=25A$	-	6	9	m $\Omega$
Forward Transconductance	$g_{fs}$	$V_{GS}=10V, I_D=10A$	-	18	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V, F=1.0\text{MHz}$	-	1160	-	pF
Output Capacitance	$C_{oss}$		-	200	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	180	-	pF
<b>Switching Characteristics<sup>(Note1)(Note2)</sup></b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V, I_D=15A, V_{GS}=10V, R_G=3.3\Omega$	-	7.5	-	nS
Turn-on Rise Time	$t_r$		-	14.5	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	35.2	-	nS
Turn-Off Fall Time	$t_f$		-	9.6	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=15V, I_{DS}=20A, V_{GS}=4.5V$	-	11.1	-	nC
Gate-Source Charge	$Q_{gs}$		-	1.85	-	nC
Gate-Drain Charge	$Q_{gd}$		-	6.8	-	nC
Gate Resistance	$R_g$	$V_{DS}=0V, V_{GS}=0V, F=1\text{MHz}$	-	2.5	-	$\Omega$
<b>Drain-Source Diode Characteristics</b>						
Coninuous Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	-	-	80	A
Pulsed Source Current <sup>(Note1)</sup>	$I_{SM}$		-	-	320	A
Forward Voltage <sup>(Note1)</sup>	$V_{SD}$	$I_S=1A, V_{GS}=0V,$	-	-	1	V

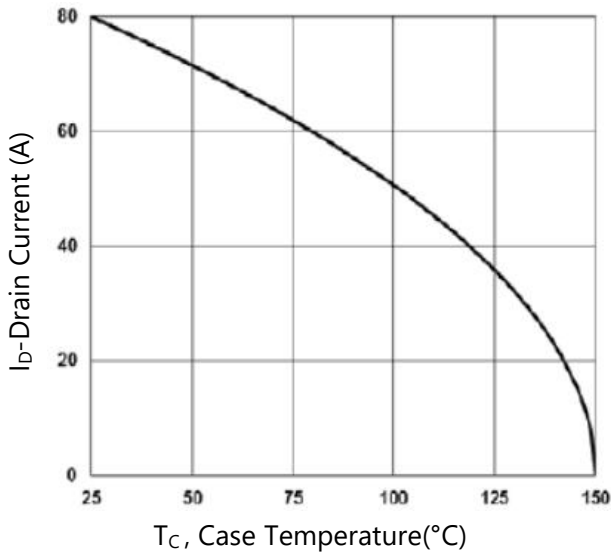
Note 1. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .

Note 2. Essentially independent of operating temperature.

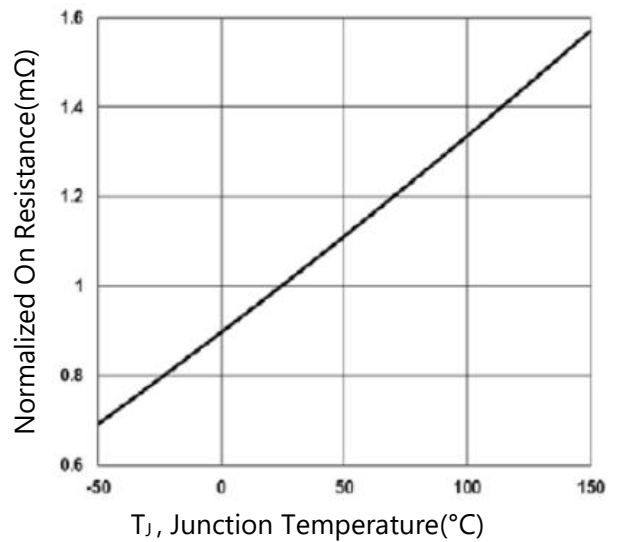


**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

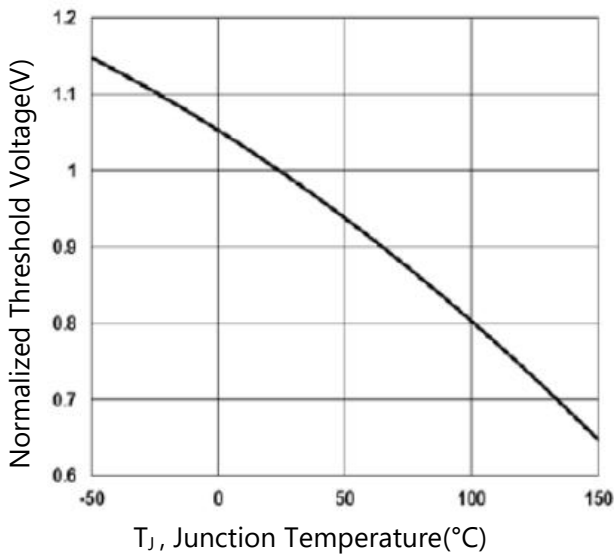
**Figure 1. Continuous Drain Current vs  $T_C$**



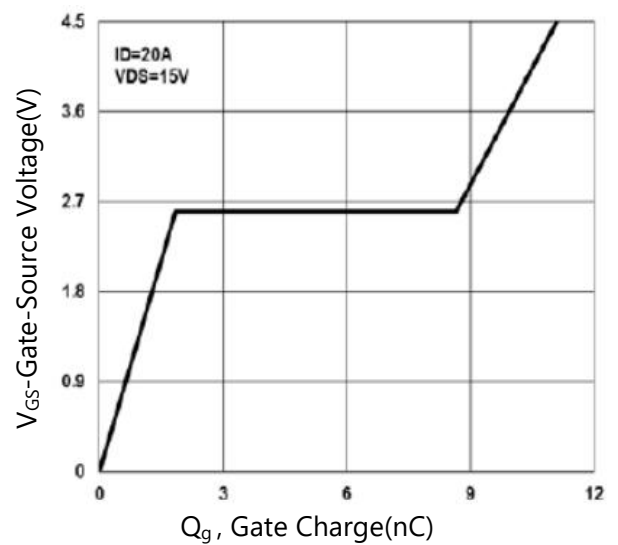
**Figure 2. Normalized  $R_{DS(on)}$  vs  $T_J$**



**Figure 3. Normalized  $V_{th}$  vs  $T_J$**



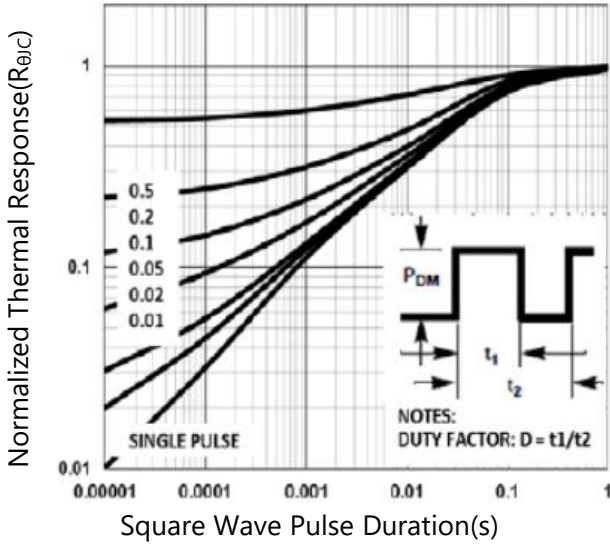
**Figure 4. Gate Charge Waveform**



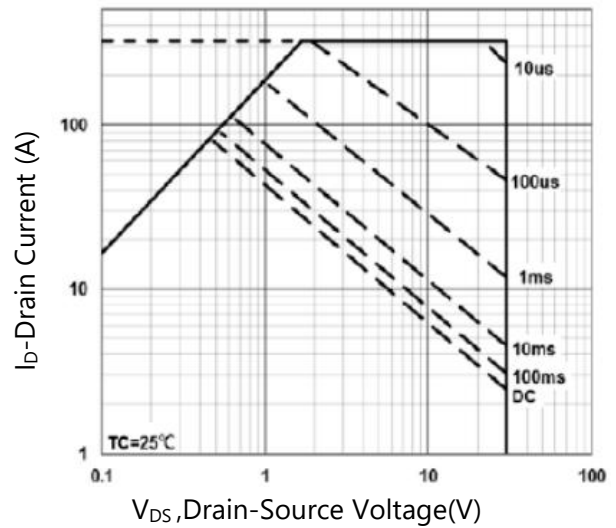


**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

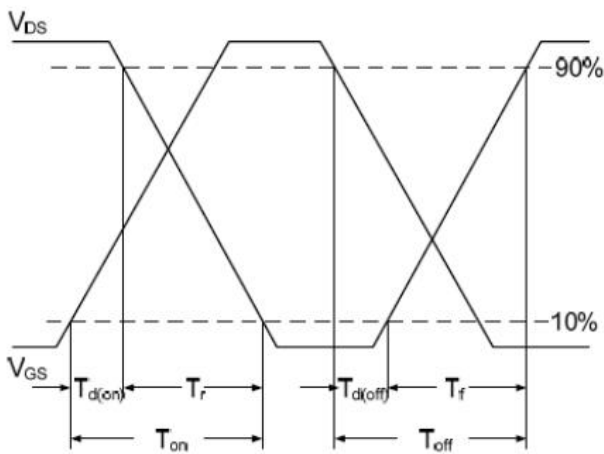
**Figure 5. Normalized Transient Impedance**



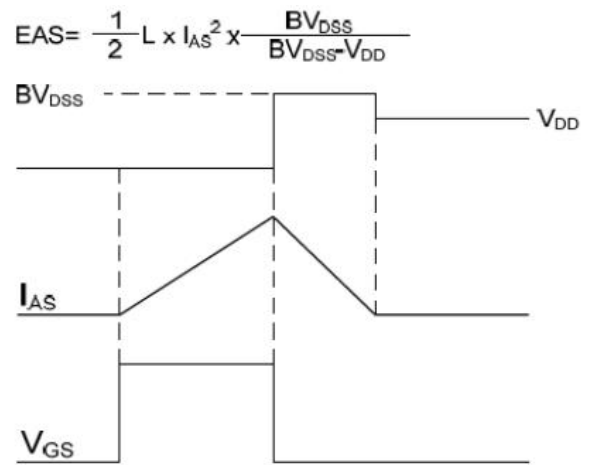
**Figure 6. Maximum Safe Operation Area**



**Figure 7. Switch Time Waveform**

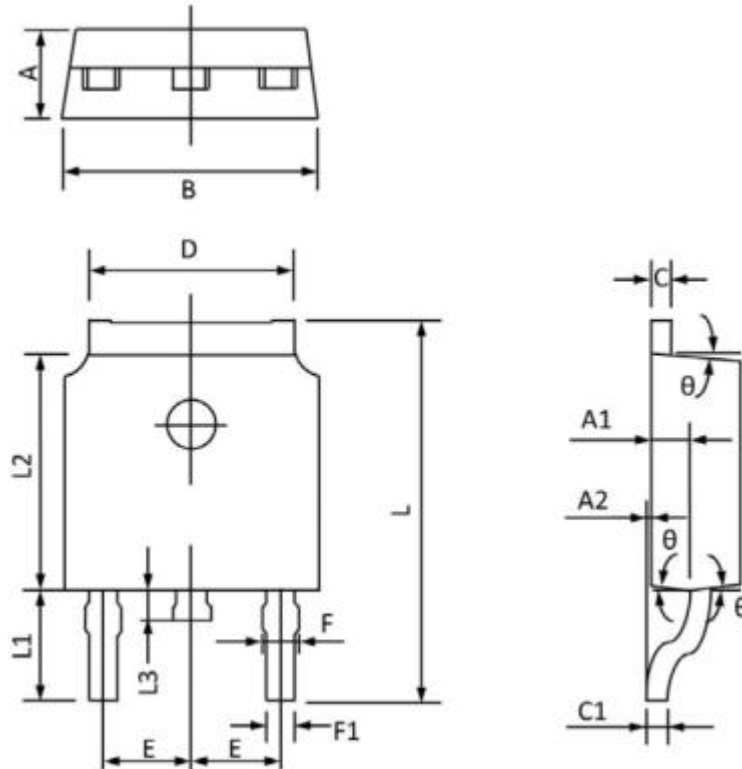


**Figure 8. EAS Waveform**



PACKAGE INFORMATION

TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	2.200	2.400	0.087	0.094
A1	0.910	1.110	0.036	0.044
A2	0.000	0.150	0.000	0.006
B	6.400	6.800	0.252	0.268
C	0.450	0.580	0.018	0.023
C1	0.450	0.580	0.018	0.023
D	5.100	5.500	0.201	0.217
E	2.186	2.386	0.086	0.094
F	0.600	0.940	0.024	0.037
F1	0.500	0.860	0.020	0.034
L	9.400	10.400	0.370	0.409
L1	2.400	3.000	0.094	0.118
L2	5.400	6.200	0.213	0.244
L3	0.600	1.200	0.024	0.047
$\theta$	3°	9°	3°	9°